

ABSTRACT

Provided are a substrate treatment method and a substrate treatment equipment enabling greater suppression of corrosion or oxidation of metal wiring exposed on a substrate surface. The present invention relates to a substrate treatment equipment (1) having a treatment chamber (2) wherein a substrate (W) is disposed, and whereto a substrate treatment solution for treating the substrate (W) is supplied. This equipment is provided with an inert gas filling mechanism (18, 39, 41) for filling with an inert gas the interior of the treatment chamber (2) wherein the substrate (W) is disposed, and, near or inside the treatment chamber (2), a catalytic unit (21) filled with a platinum-group metal catalyst wherethrough a hydrogen-dissolved water comprising hydrogen added to ultra-pure water is passed. *Obtained by passing the hydrogen-dissolved water through the platinum-group metal catalyst, a hydrogen-dissolved treatment solution is supplied as the substrate treatment solution into the treatment chamber (2) by the equipment.*